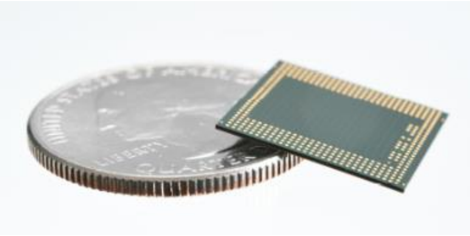
# Device Embedded Package ~MCeP®~

**MCeP (Molded Core embedded Package) is a patented and registered trademark of SHINKO ELECTRIC INDUSTRIES CO., LTD.**

## Introduction

MCeP® is a semiconductor package that contains IC chips and active/passive components. MCeP® is a compact and thin packaging solution developed by SHINKO's unique semiconductor packaging technology.
This package, having superior electrical characteristics and high reliability, is used in small-sized electronic devices and various modules.

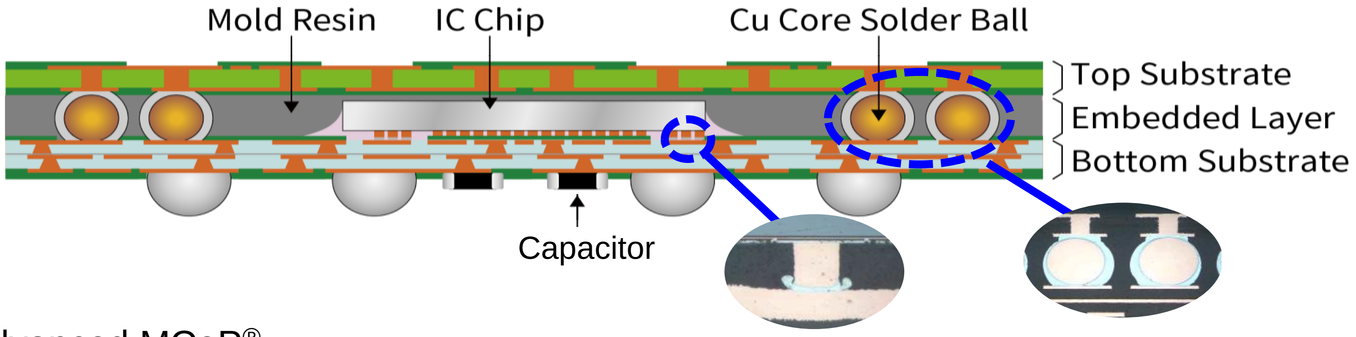


## Features

- Assembled IC chips and active/passive components using conventional assembly processes
- Robust semiconductor package structure achieving low warpage while combining small size and low-profile
- High design flexibility on the package surface
- High assembly yield and high reliability backed by a long history of mass production

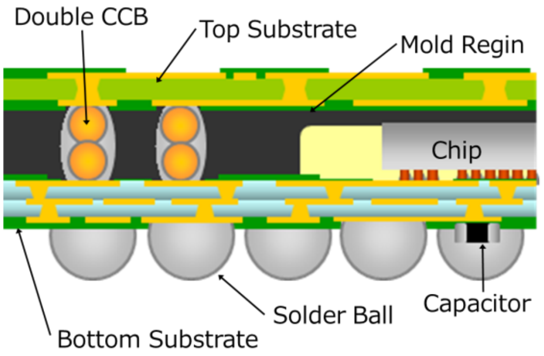
## Structure

### ■ Standard



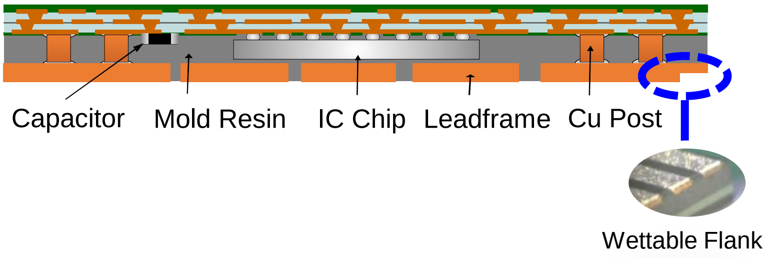
### ■ Advanced MCeP®

- Option1 : MCeP® for thicker IC chip (under development)



CCB : Copper Core Solder Ball

- Option2 : Enhanced thermal performance modules (under development)



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